NXP Semiconductors

Application Notes

Document Number: AN12108

Rev. 4, 07/2019

How to Enable Boot from QSPI Flash

1. Introduction

The <u>i.MX RT Series</u> is industry's first crossover processor provided by NXP. This document describes how to program a bootable image into the external storage device. For Information about Flashloader, MfgTool, refer to the application note <u>"How to Enable Boot from Octal SPIFlash and SD Card"AN12107.</u>

The software used for example in this document are based on the i.MXRT1050 SDK 2.4.0. The development environment is IAR Embedded Workbench 8.22.2. The hardware development environment is IMXRT1050-EVKB Board. The version of Flashloader is V1.1.

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2. MIMXRT1050 EVK board settings

2.1. EVKA Settings

In order to enable the onboard QSPI Flash features, EVK board (EVKA Board) settings need to be changed.

Step 1:

The onboard Hyper Flash should be removed, otherwise it will impact the QSPI Flash read and write timing.

Step 2:

• Weld 0Ω resistor to the pad from R153 to R158.

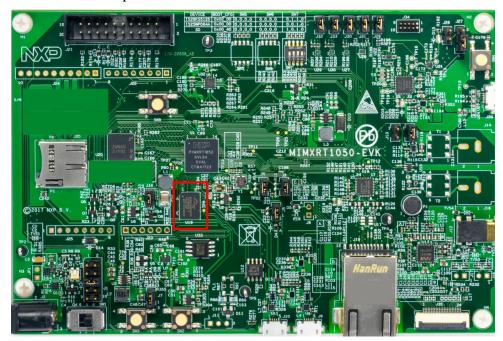


Figure 1. Hyper Flash

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Flash vcc C192 1.0UF 1.0UF

Figure 2. Weld 0 Ω resistor to the pad from R153 to R158

Step 3:

 The firmware of OpenSDA needs to be replaced. The default firmware onboard is used to Hyper Flash, so that the firmware should be replaced to QSPI Flash. Both Hyper Flash and QSPI Flash's firmware can be downloaded from NXP Website.

2.2. EVKB Settings

For EVKB board, the onboard Hyper Flash does not need to remove.

Removed resistors: R356, R361 - R366.

Weld 0Ω resistors: R153 - R158.

Follow the Step3 of Section 2.1 to update the OpenSDA firmware.

After those steps, the onboard QSPI Flash is ready to use.

NOTE

Even if QSPI flash itself doesn't have DQS pin, keep it to be floating and enable it to get a higher read/write frequency. Please refer to Table 35 and Table 36 in the RT1050 datasheet. If DQS pin is not used, only 60 MHz frequency of operation is supported while could up to 133 MHz frequency of operation if DQS pin enabled for input timing.

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SDR mode with FlexSPI $n_MCR0[RXCLKSRC] = 0x0, 0x1$

Table 35. FlexSPI input timing in SDR mode where FlexSPIn_MCR0[RXCLKSRC] = 0X0

Symbol Parameter		Min	Max	Unit
Frequency of operation		_	60	MHz
T _{IS} Setup time for incoming data		8.67	_	ns
T _{IH} Hold time for incoming data		0	_	ns

Table 36. FlexSPI input timing in SDR mode where FlexSPIn_MCR0[RXCLKSRC] = 0X1

Symbol	Parameter	Min	Max	Unit
	Frequency of operation	_	133	MHz
T _{IS}	T _{IS} Setup time for incoming data		_	ns
T _{IH} Hold time for incoming data		1	_	ns

Figure 3. SDR mode input timing parameter

2.2.1. Macros for the boot header

The <u>Table 1</u> shows three macros that are added in flexspi_nor targets to support XIP:

Table 1. Macros for the boot header

XIP_EXTERNAL_FLASH	Exclude the code which will change the clock of flexspi. make no changes.
XIP_BOOT_HEADER_ENABLE	1: Add flexspi configuration block, image vector table, boot data and device configuration data(optional) to the image by default. 0: Add nothing to the image by default.
XIP_BOOT_HEADER_DCD_ENABLE	Add device configuration data to the image. Do NOT add device configuration data to the image.

The <u>Table 2</u> shows the different effect on the built image with different combination of these macros:

Table 2. Different effect on the built image with difference macros

		XIP_BOOT_HEADER_DCD_ENA BLE=1	XIP_BOOT_HEADER_DCD_ENA BLE=0	
XIP_EXTERNAL_FLA SH=1	XIP_BOOT_HEA DER_ENABLE=1	Can be programed to Hyper Flash by IDE and can run after POR reset if Hyper Flash is the boot source. SDRAM will be initialized.	Can be programed to Hyper Flash by IDE and can run after POR reset if Hyper Flash is the boot source. SDRAM will NOT be initialized.	

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	XIP_BOOT_HEA DER_ENABLE=0	Can NOT run after POR reset if it is programed by IDE even if Hyper Flash is the boot source.
XIP_E =0	EXTERNAL_FLASH	This image can NOT do XIP because when this macro is set to 1, it will exclude the code which will change the clock of flexspi.

3. Program tools

3.1. DAP-Link (OpenSDA MSD drag/drop)

- QSPI Flash on EVK only.
- Binary file supports only.

NOTE

The default firmware of DAP-Link on EVK supports Hyper Flash only. The firmware of DAP-Link should be replaced if the QSPI flash drag/drop is used. The firmware can be downloaded from NXP Web.

3.2. MFG tool

The MfgTool supports I.MXRT BootROM and KBOOT based Flashloader, it can be used in factory production environment. The Mfgtool can detect the presence of BootROM devices connected to PC and invokes "blhost" to program the image on target memory devices connected to i.MX MCU device.

The blhost is a command-line host program used to interface with devices running KBOOT based Bootloader, part of MfgTool release .sb file support only.

4. Examples

4.1. OpenSDA Drag/Drop and boot from QSPI Flash

This chapter describes the steps needed that program an image to QSPI Flash by using OpenSDA Drag/Drop. The steps are as follows:

Step 1:

 Open the Hello world demo in the SDK and select the project configuration as flexspi_nor_debug.(Figure 4).

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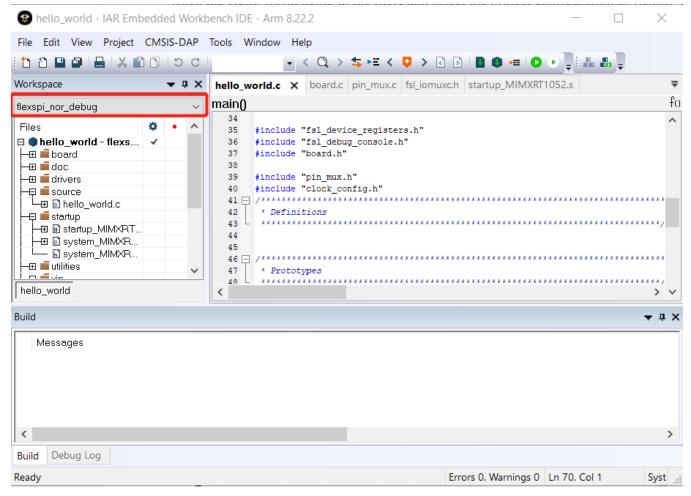


Figure 4. Select the project configuration as flexspi_nor_debug

Step 2:

• Build the project and generate an image. You can find the hello_world.bin at following location (Figure 5).

NOTE

Before an image generate, flash configure parameters need to be changed. Please refer to "How to Enable Debugging for FLEXSPI NOR Flash", AN12183

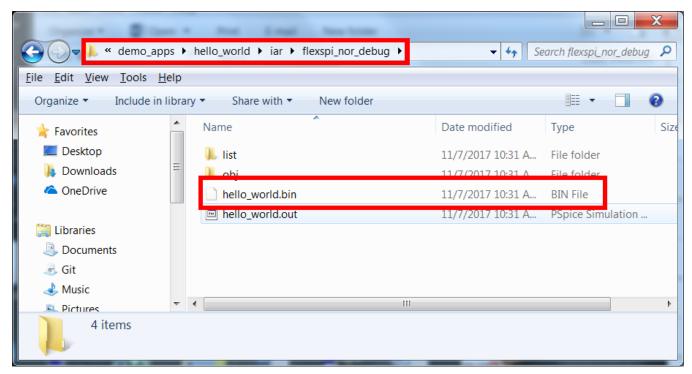


Figure 5. hello_world.bin location

Step 3:

• Configure the board to serial downloader mode and make sure the power supply is form the Debug USB. To achieve these, SW7-4 should pull-up others pull-down <u>Figure 6</u> and the J1-5, J1-6 should be connected <u>Figure 7</u>.

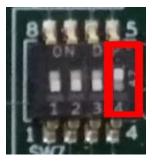


Figure 6. SW7-4 pull-up and others pull-down

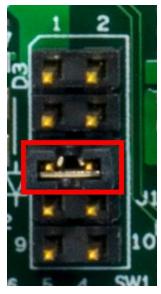


Figure 7. Power supply switch

Step 4:

• Power up the board by connecting USB Debug Cable to J28 and open windows explorer and confirm that a U-Disk appears as a drive like Figure 8.

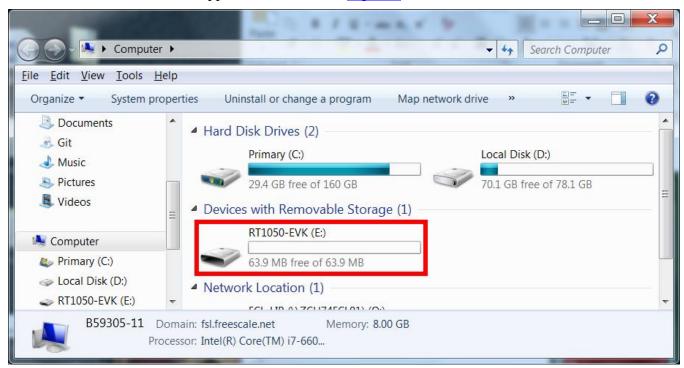


Figure 8. RT1050-EVK appeared

NOTE

The first time you connect the MBED USB to Host Computer Windows will ask to install the MBED serial driver.

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Step 5:

• Drag/Drop the hello_world.bin to RT1050-EVK. Then the RT1050-EVK disappears and after few seconds it will appear again.

Step 6:

• Disconnect the USB Debug Cable, and configure the board to QSPI Flash Boot Mode which means SW7-3 pull-up others pull-down Figure 9.

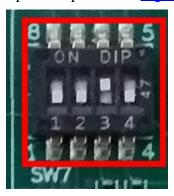


Figure 9. QSPI Flash Boot Mode Configuration

Step 7:

• Connect the USB Debug Cable again and configure the Terminal Window.

o Baud rate: 115200

o Data bits: 8

o Stop bit: 1

o Parity: None

o Flow control: None

Step 8:

• Press SW3 to reset the EVK Board and "hello world" will be printed to the terminal. Figure 10

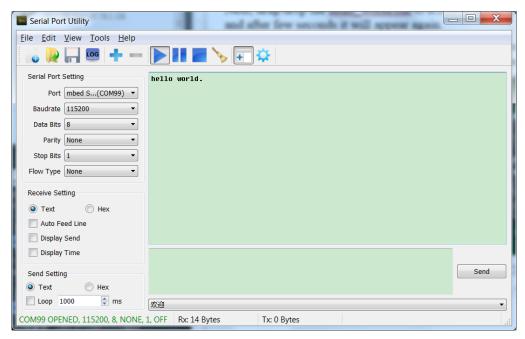


Figure 10. "hello world" be printed to the terminal

4.2. MFG Boot from QSPI Flash

This chapter describes the steps that using MFG tool to program an image to QSPI Flash and boot from the QSPI Flash.

Step 1:

• Open the Hello world demo in the SDK and select the project configuration as flexspi_nor_debug <u>Figure 11</u> and make sure the settings likes <u>Figure 12</u>.

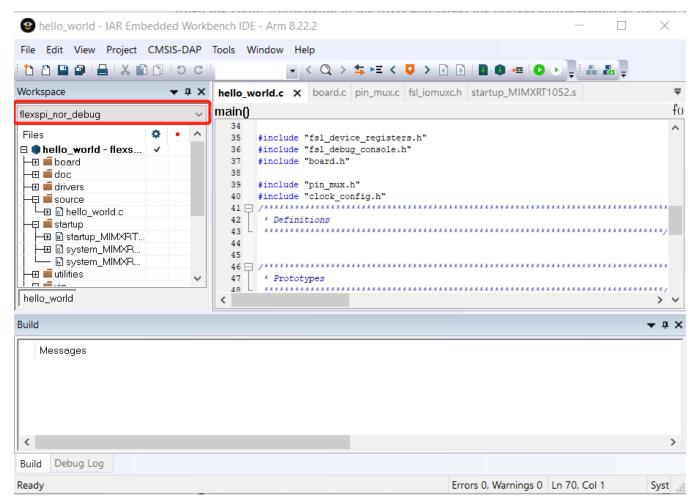


Figure 11. Select the project configuration as flexspi_nor_debug

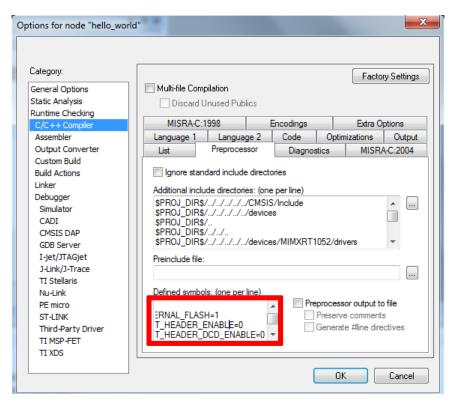


Figure 12. Defined Symbols for hello_world

Step 2:

12

Change the default entry to Reset_Handler likes following Figure.

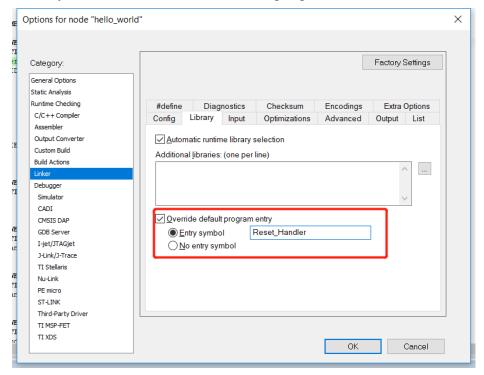


Figure 13. Change the default entry to Reset_Handle

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NOTE

Step 5 can be skipped if this step is set.

Step 3:

• Build the project and generate the image. You can find the *hello_world.srec* at following location Figure 14.

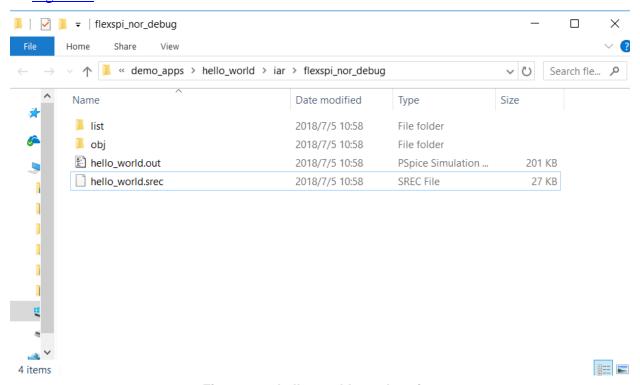


Figure 14. hello_world.srec location

Step 4:

• Copy hello_world.srec to the elftosb folder:

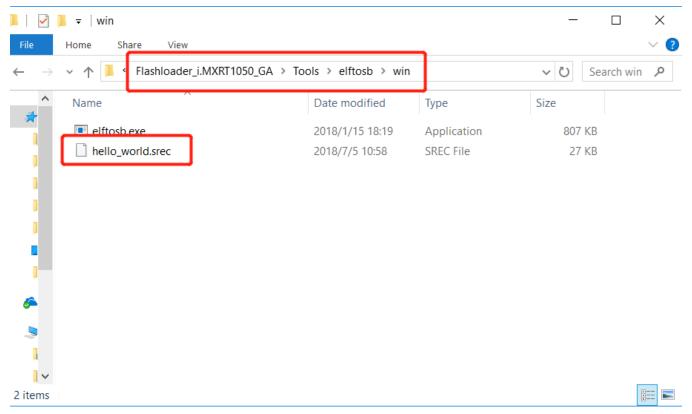


Figure 15. Copy hello_world.srec

Step 5:

Open the *imx-flexspinor-normal-unsigned.bd* under path *Flashloader_i.MXRT1050_GA\Tools\bd_file\imx10xx*. Open it and set the entryPointAddress to

0x60002000 likes following Figure.

```
options {
 2
        flags = 0x00;
 3
        startAddress = 0x60000000;
 4
        ivtOffset = 0x1000;
 5
        initialLoadSize = 0x2000;
 6
        # Note: This is required if the default entrypoint is not the
 7
                Please set the entryPointAddress to Reset Handler add
 8
        entryPointAddress = 0x60002000;
 9
10
11
    sources {
12
        elfFile = extern(0);
13
14
15
   section (0)
16
   {
17
18
```

Figure 16. Set the entryPointAddress to 0x60002000

NOTE

Step 2 can be skipped if this step is set.

Step 6:

• Now we can use command to generate the i.MX Bootable image using elftosb file. Open cmd.exe and type following command:

elftosb.exe -f imx -V -c ../../bd_file/imx10xx/imx-flexspinor-normal-unsigned.bd -o ivt_flexspi_nor_hello_world.bin hello_world.srec

Figure 17. Generate i.MX Bootable image

After above command, two bootable images are generated:

- ivt_flexspi_nor_hello_world.bin
- ivt_flexspi_nor_hello_world_nopadding.bin

ivt_flexspi_nor_hello_world.bin:

The memory regions from 0 to ivt_offset are filled with padding bytes (all 0x00s).

ivt_flexspi_nor_hello_world_nopadding.bin:

Starts from ivtdata directly without any padding before ivt.

The later one will be used to generate SB file for QSPI Flash programming in subsequent section.

Step 7:

Open cmd.exe and type following command:

elftosb.exe -f kinetis -V -c ../../bd_file/imx10xx/program_flexspinor_image_qspinor.bd -o boot_image.sb ivt_flexspi_nor_hello_world_nopadding.bin

```
Windows PowerShell
                     5\Desktop\Flashloader i.MXRT1050 GA\Flashloader i.MXRT1050 GA\Flashloa
PS C:\Users\
n> .\elftosb.exe -f imx -V -c ../../bd_file/imx10xx/imx-flexspinor-normal-unsigned.bd -o
ivt_flexspi_nor_hello_world.bin hello_world.srec
         Section: 0x0
iMX bootable image generated successfully
PS C:\Users\-
                      \Desktop\Flashloader_i.MXRT1050_GA\Flashloader_i.MXRT1050_GA\Flashloa
der_RT1050_1.1\Tools\elftosb\win>.\elftosb.exe -f kinetis -V -c ../../bd_file/imx10xx/pr ogram_flexspinor_image_qspinor.bd -o boot_image.sb ivt_flexspi_nor_hello_world_nopadding.
Boot Section 0x00000000:
  FILL
         adr=0x00002000
                             1en=0x00000004
                                                ptn=0xc0000006
  ENA
          adr = 0x00002000
                             cnt=0x000000004
                                                f1g=0x0900
  ERAS
          adr=0x60000000
                             cnt=0x00010000
                                                f1g=0x0000
                             1en=0x00000004
                                                ptn=0xf000000f
         adr=0x00003000
  FILL
         adr=0x00003000
                             cnt=0x00000004
  ENA
                                                f1g=0x0900
                             1en=0x000032b4
                                                crc=0x9958d743 | f1g=0x0000
  LOAD
         adr=0x60001000
PS C:\Users\
                      \Desktop\Flashloader i.MXRT1050 GA\Flashloader i.MXRT1050 GA\Flashloa
der RT1050 1.1\Tools\elftosb\win>
```

Figure 18. Create a SB file for QSPI Flash programming

After performing above command, the boot_image.sb is generated under elftosb folder Figure 19.

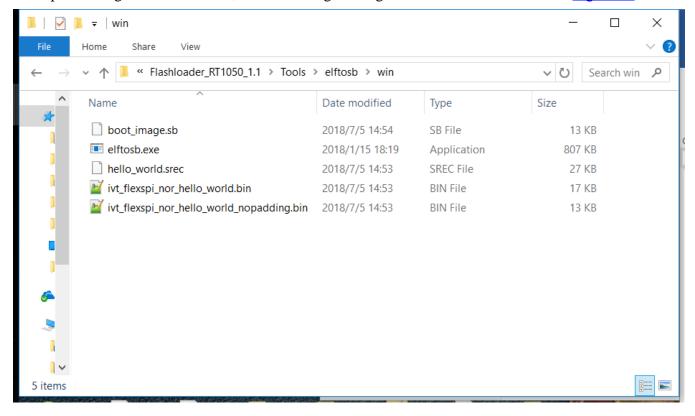


Figure 19. The boot image.sb is generated

Step 8:

• Copy the boot_image.sb file to OS Firmware folder:

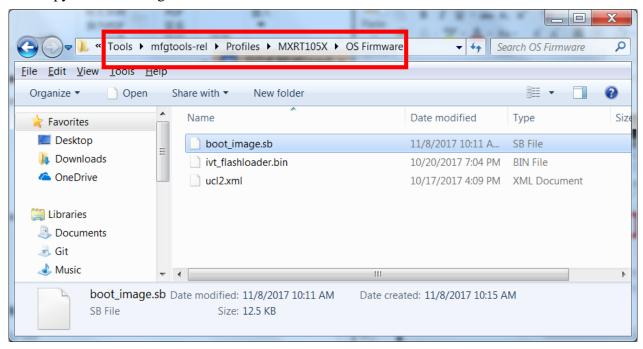


Figure 20. Copy the boot_image.sb to OS Firmware folder

Now, make sure the "name" under "[List]" to "**MXRT105x-DevBoot**" in *cfg.ini* file under <*mfgtool_root_dir>* folder.

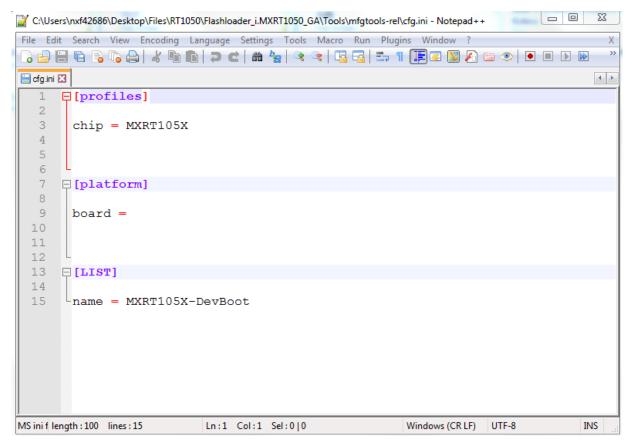


Figure 21. Make sure the name to "MXRT105x-DevBoot"

Switch the EVK-Board to Serial Downloader mode by setting SW7 to "1-OFF, 2-OFF, 3-OFF, 4-ON". Connect a UAB Cable to J9 and power on the EVK Board by inserting USB Cable to J28. Open MfgTool, it will show the detected device like <u>Figure 22</u>.

NOTE

In some corner case, HID-compliant device is not recognized which is because the PC only have USB root device and no USB hub device, and this software limitation will be fixed in near future, the workaround at this moment is to use external USB hub as extension.

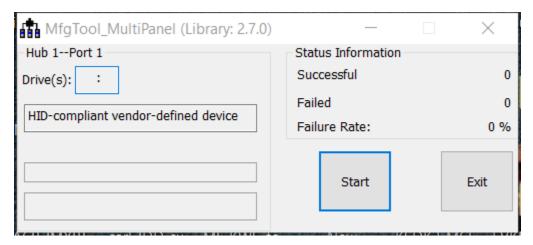


Figure 22. MfgTool GUI with device connected

Click **Start**. Mfgtool initiates and prompts the success status as shown in <u>Figure 23</u>. Click **Stop** and close the Mfgtool.

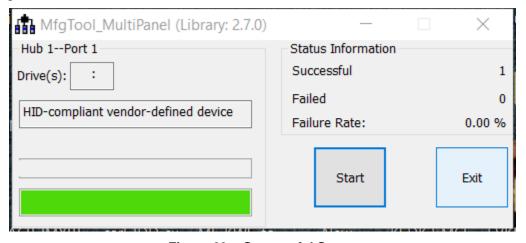


Figure 23. Successful Status

Step 9:

• Switch the RT1050-EVK board to Internal boot mode and select QSPI Flash as boot device by setting SW7 to "1-OFF, 2-OFF, 3-ON, 4-OFF". Connect the USB Cable to J28 and open a terminal, then reset the Board. We can see that "hello world" will be printed to the terminal.

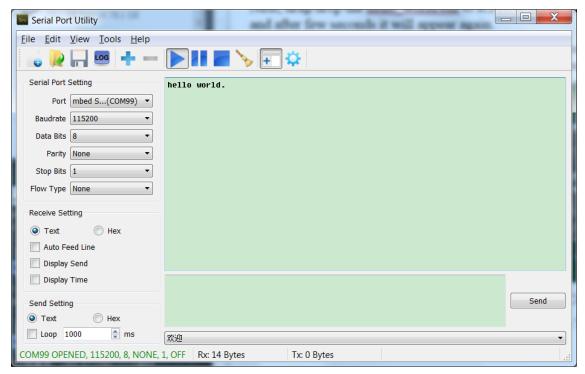


Figure 24. "hello world" be printed to the terminal

4.3. MFG Boot from QSPI Flash with DCD for SDRAM

For steps, please refer to "How to Enable Boot from Octal SPIFlash and SD Card", AN12107.

5. QSPI Flash support list

Besides the EVK onboard QSPI Flash, the following Flashes are also supported and please note those are just typical examples with those flash vendors, theoretically we could support all the flash memory that comply with JESD216/JESD216A/JESD216B.

At the same time, the RT1050EVK could support both 1.8 V and 3.3 V SPI flash device by switching the FLASH_VCC power supply as below <u>Figure 25</u> shows. If 3.3 V SPI flash is mounted, you need mount R301 and DNP R49, otherwise you need mount R49 and DNP R301.

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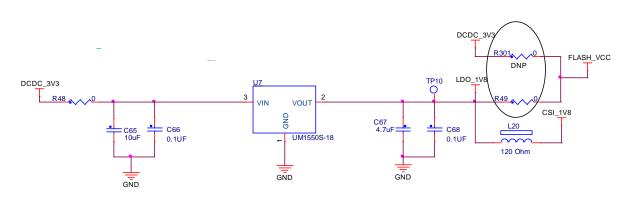


Figure 25. FLASH_VCC switching

Vendor Flash Part Number Voltage 3.3 V MX25L6433F Macronix Macronix MX25U6435E 1.8 V ISSI IS25LP064A-JBLE 3.3 V IS25WP064AJBLE ISSI 1.8 V GD25Q64C 3.3 V GigaDevice GD25LQ64C, GD25LT256E, GD25LB256E 1.8 V GigaDevice WINBOND W25Q64JV 3.3 V WINBOND W25Q64FW 1.8 V Micron MT25QL128ABA1ESE-0SIT 3.3 V Micron MT25QU128ABA1ESE-0SIT 1.8 V Adesto AT25QF641-SUB-T 3.3 V Adesto AT25QL641-SUE-T 1.8 V

Table 3. QSPI Flash support list

6. Conclusion

This application note mainly describes how to use Flashloader step by step. For more information, refer to "i.MX MCU Manufacturing User's Guide" and "How to Enable Boot from Octal SPIFlash and SD Card".

7. Revision history

Table 4. Revision history

Revision number	Date	Substantive changes
0	12/2017	Initial release
1	06/2018	Adapted SDK version 2.3.1 and Flashloader version 1.1. In Table 1. QSPI Flash support list, changed MX25U6433F to MX25L6433F.
2	07/2018	 Added steps to change the entry address. Used srec file instead of .out file as the source file.
3	09/2018	Updated Table 3 QSPI Flash support list.
4	07//2019	Updated Table 3 QSPI Flash support list.

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